

CLAIMS

What is claimed is:

1. A shipping package having a plurality of semiconductor die stacks thereon, the  
5 shipping package being adapted to temporarily hold the plurality of semiconductor die  
stacks.

10 2. The shipping package, as set forth in claim 1, comprising a tape reel having the  
plurality of semiconductor die stacks thereon.

15 3. The shipping package, as set forth in claim 1, comprising a gel pack having the  
plurality of semiconductor die stacks thereon.

4. The shipping package, as set forth in claim 1, comprising a tray having the plurality  
of semiconductor die stacks thereon.

20

5. The shipping package, as set forth in claim 1, wherein each of the die stacks comprises at least two semiconductor die, each of the semiconductor die being coupled together by an adhesive.

5

6. The shipping package, as set forth in claim 5, wherein one of the at least two semiconductor die is thicker than a second of the at least two semiconductor die.

10 7. The shipping package, as set forth in claim 5, wherein the topside surface area of one of the at least two semiconductor die is less than the topside surface area of a second of the at least two semiconductor die.

15 8. The shipping package, as set forth in claim 5, wherein the stack of at least two semiconductor die is configured such that the stack comprises a shingle stack.

20 9. The shipping package, as set forth in claim 5, wherein at least one of the at least two semiconductor die comprises a memory die.

10. A tape reel having a plurality of semiconductor die stacks thereon, the tape reel  
being adapted to temporarily hold the plurality of semiconductor die stacks.

5 11. The tape reel, as set forth in claim 10, wherein each of the die stacks comprises at  
least two semiconductor die, each of the semiconductor die being coupled together by an  
adhesive.

10 12. The tape reel, as set forth in claim 11, wherein one of the at least two  
semiconductor die is thicker than a second of the at least two semiconductor die.

15 13. The tape reel, as set forth in claim 11, wherein the topside surface area of one of  
the at least two semiconductor die is less than the topside surface area of a second of the  
at least two semiconductor die.

20 14. The tape reel, as set forth in claim 11, wherein the stack of at least two  
semiconductor die is configured such that the stack comprises a shingle stack.

15. The tape reel, as set forth in claim 11, wherein at least one of the at least two semiconductor die comprises a memory die.

5 16. A gel pack having a plurality of semiconductor die stacks thereon, the gel pack being adapted to temporarily hold the plurality of semiconductor die stacks.

10 17. The gel pack, as set forth in claim 16, wherein each of the die stacks comprises at least two semiconductor die, each of the semiconductor die being coupled together by an adhesive.

15 18. The gel pack, as set forth in claim 16, wherein one of the at least two semiconductor die is thicker than a second of the at least two semiconductor die.

20 19. The gel pack, as set forth in claim 16, wherein the topside surface area of one of the at least two semiconductor die is less than the topside surface area of a second of the at least two semiconductor die.

20. The gel pack, as set forth in claim 16, wherein the stack of at least two semiconductor die is configured such that the stack comprises a shingle stack.

5 21. The gel pack, as set forth in claim 16, wherein at least one of the at least two semiconductor die comprises a memory die.

10